

	Type	Hits	Search Text	DBs	Time Stamp
1	IS&R	6	((("5408567") or ("4537469") or ("5499732"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2004/11/08 18:39
2	BRS	982	"385"/.ccls. and resin and embed\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2004/11/08 18:39
3	BRS	262	"385"/.ccls. and resin with embed\$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2004/11/09 12:53
4	BRS	47	"385"/.ccls. and (resin with embed\$3 with(board\$1 or substrate\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2004/11/09 14:33
5	BRS	0	"385"/.ccls. and (resin with embed\$3 with (printed adj circuit\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2004/11/09 13:49
6	BRS	0	"385"/.ccls. and (composite with embed\$3 with (printed adj circuit\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2004/11/09 13:58
7	BRS	0	"385"/.ccls. and ((composite with embed\$3) same (printed adj circuit\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2004/11/09 13:58
8	BRS	2	"385"/.ccls. and ((resin with embed\$3) same (printed adj circuit\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2004/11/09 14:12
9	BRS	1	"385"/.ccls. and (resin with embed\$3 with(wiring adj (board\$1 or substrate\$1)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2004/11/09 14:21
10	BRS	789	"385"/.ccls. and (embed\$3 with (board\$1 or substrate\$1))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2004/11/09 14:34
11	BRS	130	"385"/.ccls. and (embed\$3 with (circuit\$1 with (board\$1 or substrate\$1)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2004/11/09 14:37
12	BRS	10	"385"/.ccls. and (((resin\$1 or composite\$1 or filler\$1 or gel\$1) with embed\$3) with (circuit\$1 with (board\$1 or substrate\$1)))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	2004/11/09 14:38
13	BRS	1	"6233376".PN.	USPAT; USOCR	2004/11/09 14:41